

PCN Number:	20140221000	PCN Date:	02/28/2014
Title:	Wafer Diameter Change for Select Devices in the CS150 Process at GFAB		
Customer Contact:	PCN Manager:	Phone:	Dept:
		+1(214)480-6037	Quality Services
*Proposed 1st Ship Date:	05/28/2014	Estimated Sample Availability:	Date Provided at Sample request
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials
		<input checked="" type="checkbox"/>	Wafer Fab Process
	<input type="checkbox"/>	Part number change	
PCN Details			
Description of Change:			
This change notification is to announce a wafer diameter change for select devices in the CS150 process at GFAB.			
Current		New	
Site/Process/Wafer Diameter		Site/Process/Wafer Diameter	
GFAB6/CS150 Process/150mm		GFAB8/CS150 Process/200mm	
The CS150 process technology was previously qualified at GFAB and has been running successfully since 2008.			
Reason for Change:			
Continuity of supply.			
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):			
None			

Changes to product identification resulting from this PCN:		
<i>Note: This is <u>not</u> a fab site change. GFAB6 and GFAB8 are in the same location. The CSO is the differentiator between 6" (150mm) and 8" (200mm).</i>		
Current		
Chip Site	Chip site code (20L)	Chip country code (21L)
GFAB6	GF6	GBR
New		
Chip Site	Chip site code (20L)	Chip country code (21L)
GFAB8	GF8	GBR

Sample Product Shipping Label (not actual product label)

				(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS
MADE IN: Malaysia 2DC: 2Q:		SEAL DT 03/29/04		
MSL 2 / 260C / 1 YEAR MSL 1 / 235C / UNLIM	OPT: ITEM: 39 LBL: 5A (L) T0:1750			

Product Affected:

ADC12030CIWM/NOPB	COPC881-CAU/WM/E7001172	HPC36003V20/NOPB
ADC12030CIWMX/NOPB	COPC881-CFS/WM/E7001333	HPC36083DUI/V20/NOPB
ADC12038CIWM	COPC881-CLQ/WM/E7001130	HPC46003V20
ADC12038CIWM/NOPB	COPC881-CON/WM/E7001270	HPC46003V20/63
ADC12038CIWMX/NOPB	COPC882-CLN/WM/E7001131	HPC46003V20/63SN
ADC12130CIWM	COPC922-DNG/WM	HPC46003V20/NOPB
ADC12130CIWM/NOPB	COPC922-DNG/WM/EPDB1785	HPC46083TXQ/V30/SP108663
ADC12130CIWMX/NOPB	COPCH922-DOD/WM/E7000836	HPC46400EV20/NOPB
ADC12138CIMSAX/NOPB	COPCH922-DOD/WM/NOPB	HPC46400EV20/S7001136
ADC12138CIWM	COPCJ842-CFA/WM/E7000908	LM12458CIV
ADC12138CIWM/NOPB	COPCJ842-CGT/WM/EPDB2102	LM12458CIV/NOPB
ADC12138CIWMX/NOPB	COPCJ842-CGT/WM/NOPB	LM12458CIVX
ADC12138CIWMX/NOPB	COPCJ842-CHM/WM/E7000938	LM12458CIVX/NOPB
ADC12H034CIMSAX	COPCJ842-CNQ/WM/E7000961	LM12H458CIV
ADC12H034CIMSAX/NOPB	COPCJ940-CCS/WM/E7001214	LM12H458CIV/NOPB
ADC12H034CIMSAX	COPCJ940-CCS/WM/NOPB	LM12H458CIVF
ADC12H034CIMSAX/NOPB	COPCJH942CGJ/WM/E7000857	LM12H458CIVF/NOPB
COPC822-ANC/WM/S7001238	COPEG884-AQC/WM/SP110451	LM12L458CIV
COPC822-APN/N/SP110434	COPEG884-CEK/WM/E7000968	LM12L458CIV/NOPB
COPC822-CEG/WM/E7001181	COPEG884-CHP/WM/E7001546	TP3070V-G
COPC822-CNH/WM/E7000887	COPEG884-CHP/WM/NOPB	TP3070V-G/63SN
COPC822-DQZ/WM/E7001168	COPEG888-CDP/V/E7001243	TP3070V-G/NOPB
COPC822-DQZ/WM/NOPB	DP83910AV/63	TP3070V-XG
COPC822-FHM/WM/SP110623	DP83910AV/63SN	TP3070V-XG/NOPB
COPC881-AJV/N/SP110088	DP83910AV/NOPB	TP3071N-G
COPC881-AWX/WM/E7002115	HPC36003V20	TP3071N-G/NOPB

Qualification Data (Approved: 01/30/2014)

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device 1: ADC12138CIMS A

Wafer Fab Site:	GFAB8	Wafer Fab Process:	CS150
Wafer Diameter:	200mm		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results			
Reliability Test	Conditions	Sample Size/Fails	
		Lot#1	Lot#2
		Lot#3	
Life Test	125°C (1000 Hrs)	80/0	-
		-	-
Early Life Failure Rate	125°C (48 Hrs)	400/0	-
		-	-

Reference Qual Data: CS200/CS150 process flow in GFAB (Approved 12/19/2011)

Qualification Device: ADC12138CIMS A

Wafer Fab Site:	GFAB8	Wafer Fab Process:	CS150	
Wafer Diameter:	200mm			
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fails		
		Lot#1	Lot#2	Lot#3
Early Life Failure Rate	125°C (48 Hrs)	800/0	-	-
Operating Life	125°C (1000 Hrs)	80/0	-	-
**Temp Cycle	-65°C – 150°C (500 Cycles)	80/0	80/0	80/0
**Autoclave	121°C 100% 14.7PSI (96 Hrs)	79/0	80/0	79/0
**Biased HAST	130°C 85% 33.3PSI (96 Hrs)	80/0	80/0	80/0
HTSL	150°C (1000 Hrs)	79/0	-	-
GTLK	155°C (+/-400V)	3/0	-	-
** Preconditioning sequence: (Level 3/260C) as per JESD22-A113				

Qualification Device: ADC10064CIWM

Wafer Fab Site:	GFAB8	Wafer Fab Process:	CS200	
Wafer Diameter:	200mm			
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fails		
		Lot#1	Lot#2	Lot#3
Early Life Failure Rate	125°C (48 Hrs)	799/0	799/0	-
Operating Life	125°C (1000 Hrs)	80/0	80/0	-
**Temp Cycle	-65°C – 150°C (500 Cycles)	78/0	-	-
ESD CDM	750V	3/0	3/0	-
ESD HBM	2000V	3/0	3/0	-
ESD MM	250V	3/0	3/0	-
LUPS	25°C, 85°C, 150°C	12/0	-	-
** Preconditioning sequence: (Level 3/260C) as per JESD22-A113				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com